504698639 12/20/2017

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 EPAS ID: PAT4745361 Stylesheet Version v1.2

 SUBMISSION TYPE:
 NEW ASSIGNMENT

 NATURE OF CONVEYANCE:
 ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chun-Hao Lin	12/15/2017
Hsin-Yu Chen	12/15/2017
Shou-Wei Hsieh	12/15/2017

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15849599

CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER:	NAUP3187USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	12/20/2017

Total Attachments: 6

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PATENT 504698639 REEL: 044454 FRAME: 0860

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PATENT REEL: 044454 FRAME: 0861

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	eby declare that:			
☑ The attached application, or				
☐ United States application nu	ımber	filed	on	, or
☐ PCT international application	n number	file	ed on	
The above-identified application was	s made or authorized to be	e made by me.		
l believe that I am the original invent application.	tor or an original joint inve	ntor of a claime	d invention	in the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	ıl false statement made in isonment of not more tha	this declaration n five (5) years,	n is punisha or both.	able
In consideration of the payment by	UNITED MICROELECORP.	CTRONICS	having a	postal address of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Pa	rk, Hsin-Chu	City 300	, Taiwan, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good are			receipt of v	vhich is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, an	nd to any and all improvel ation and, in and to, all Let r any continuations, contir	ments which ar ters Patent to b nuation-in-part,	e disclosed e obtained divisions, r	in the for said enewals,
I hereby covenant that no assignme entered into which would conflict wit	nt, sale, agreement or end h this assignment;	cumbrance has	been or wi	ll be made or
I further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will to related thereto and will promptly exe	ntion and said Letters Pate estify as to the same in an	ent and legal ed y interference,	quivalents a litigation pr	as may be
representatives any and all papers, maintain, issue and enforce said appequivalents thereof which may be not IN WITNESS WHEREOF, I have he	plication, said invention ar ecessary or desirable to ca	nd said Letters l arry out the pro	Patent and	said
Note: An application data sheet (PTo				

Page 1 of 6

NPO#NAU-P3187-USA:0 CUST#UMCD-2017-0566 F#NPO-P0002E-US1201 DSB0-106U028120

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Chun-Hao Lin	Date:	DEC 1 5 2017	
Signature:	Chun Har	Lin		

Page 2 of 6

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	mber	filed o	on	, or
☐ PCT international application	n number	file	ed on	
The above-identified application was	made or authorized to be ma	de by me.	***************************************	
I believe that I am the original invent application.	or or an original joint inventor	of a claime	d invention i	n the
l hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this isonment of not more than five	declaration (5) years,	n is punishat or both.	ole
In consideration of the payment by	UNITED MICROELECTR	RONICS	having a p	ostal address of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Park, l	Hsin-Chu	_ City 300,	Taiwan, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ nd valuable consideration.	1.00), the	receipt of wh	nich is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvement tion and, in and to, all Letters r any continuations, continuati	s which are Patent to b on-in-part,	e disclosed i e obtained f divisions, rei	n the or said newals.
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumb n this assignment;	orance has	been or will	be made or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent a estify as to the same in any inte	nd legal ed erference, l	juivalents as litigation pro	mav be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	olication, said invention and sa ecessary or desirable to carry o	id Letters Fout the prop	Patent and sooses therec	aid of. (Date of signing)
Note: An application data sheet (PT0 inventive entity, must accompany thi	D/SB/14 or equivalent), includi s form. Use this form for each	ing naming additional	the entire	

Page 3 of 6

NPO#NAU-P3187-USA:0 CUST#UMCD-2017-0566 F#NPO-P0002E-US1201 DSB0-106U028120

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Hsin-Yu Chen	Date:	DEC 15 2017	
Signature:	Hon Inden	W. W		

Page 4 of 6

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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The above-identified application was	made or authorized to be ma	de by me.		
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hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this isonment of not more than five	declaration (5) years,	is punishable or both.)
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referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ ad valuable consideration.	1.00), the	receipt of whic	ch is hereby
hereby sell, assign and transfer to A he entire right, title and interest in an nvention as above-identified applica nvention by the above application or substitutes, or extensions thereof, an	nd to any and all improvement tion and, in and to, all Letters l any continuations, continuation	s which are Patent to be on-in-part, o	e disclosed in the disc	the · said ewals.
hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumb n this assignment;	rance has	been or will be	e made or
further covenant that ASSIGNEE wi and documents relating to said inven anown and accessible to I and will te elated thereto and will promptly exec	ition and said Letters Patent a stify as to the same in any inte	nd legal eq erference, li	uivalents as n	nav be
epresentatives any and all papers, in naintain, issue and enforce said app equivalents thereof which may be ne N WITNESS WHEREOF, I have her	lication, said invention and sa cessary or desirable to carry o	id Letters F out the prop	Patent and said poses thereof.	d Date of signing)
lote: An application data sheet (PTC				

Page 5 of 6

NPO#NAU-P3187-USA:0 CUST#UMCD-2017-0566 F#NPO-P0002E-US1201 DSB0-106U028120

Docket No NAUP3187USA

LEGAL NAM	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Shou-Wei Hsieh	Date:	DEC 1 5 2017	
Signature:	Show- Wei Heil			

Page 6 of 6

NPO#NAU-P3187-USA:0 CUST#UMCD-2017-0566

RECORDED: 12/20/2017

F#NPO-P0002E-US1201 DSB0-106U028120

PATENT REEL: 044454 FRAME: 0867